



Material Content Data Sheet



Sales Product Name		BTS5090-2EKA		Issued		9. January 2019		
MA#		MA001259210						
Package		PG-DSO-14-40		Weight*		149.59 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.875	1.92	1.92	19216	19216
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		116	
	non noble metal	zinc	7440-66-6	0.070	0.05		465	
	non noble metal	iron	7439-89-6	1.392	0.93		9304	
wire	non noble metal	copper	7440-50-8	56.512	37.78	38.77	377770	387655
	non noble metal	copper	7440-50-8	0.781	0.52	0.52	5223	5223
	encapsulation	organic material	carbon black	1333-86-4	0.169	0.11		1129
plastics	plastics	epoxy resin	-	7.766	5.19		51912	
	inorganic material	silicondioxide	60676-86-0	76.476	51.13	56.43	511224	564265
leadfinish	non noble metal	tin	7440-31-5	1.226	0.82	0.82	8197	8197
plating	noble metal	silver	7440-22-4	1.417	0.95	0.95	9476	9476
glue	plastics	epoxy resin	-	0.156	0.10		1044	
	noble metal	silver	7440-22-4	0.737	0.49	0.59	4924	5968
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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